

What is claimed is:

1. A polishing apparatus comprising:

a polishing table having a polishing surface;

5 a top ring for holding a substrate and pressing a surface of the substrate against said polishing surface to polish said surface of said substrate;

at least one optical measuring device disposed adjacent to the outer peripheral portion of said polishing table and  
10 below said polishing surface of said polishing table for measuring the thickness of a layer formed on said surface of said substrate; and

at least one notch formed in the peripheral portion of said polishing table, said notch allowing light emitted from  
15 said optical measuring device to pass therethrough and be incident on said surface of said substrate and allowing light reflected from said surface of said substrate to pass therethrough and be incident on said optical measuring device.

20 2. A polishing apparatus according to claim 1, wherein said substrate has a semiconductor device thereon.

3. A polishing apparatus according to claim 1, wherein said top ring is swingable between an inner area and an outer  
25 area on said polishing table so that the light emitted from said optical measuring device is incident on a position ranging from the outer circumferential edge to the central portion of said substrate.

4. A polishing apparatus according to claim 1, wherein  
when said top ring is swung to a maximum, the area of said  
substrate which projects outwards beyond the outer  
5 circumferential edge of said polishing table is not more than  
40% of the entire area of said surface, being polished, of  
said substrate.

5. A polishing apparatus according to claim 1, further  
10 comprising a nozzle for supplying a cleaning liquid to said  
optical measuring device.

6. A polishing apparatus comprising:  
a polishing table having a polishing surface;  
15 a top ring for holding a substrate to polish the  
substrate by a relative motion between the substrate and said  
polishing surface;

at least one optical measuring device for measuring the  
thickness of a layer formed on said surface of the substrate  
20 by applying light to said surface of the substrate; and

a moving mechanism for moving at least one of said top  
ring and said polishing table during polishing operation;

wherein said moving mechanism moves said top ring or  
said polishing table to the position where the central portion  
25 of the substrate is exposed toward said optical measuring  
device, for allowing said optical measuring device to measure  
the central portion of the substrate.